

30V/25mΩ@10V N-Channel MOSFET

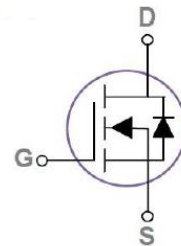
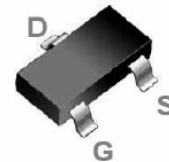
Features

- VDS(max)=30V
- ID(max)=5.0A
- RDS(ON) <25mΩ(max)@VGS = 10V
- RDS(ON) <42mΩ(max)@VGS = 4.5V
- Improved dv/dt capability
- Green Device Available
- Fast switching

Applications

- MB / VGA / Vcore
- Hand-Held Instrument
- Load Switch

SOT23 Pin Configuration



Maximum Ratings (Tc = 25°C, Unless Otherwise Noted)

Parameters	Symbol	Limits	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current - Continuous(TC=25°C)	I _D	5	A
Drain Current - Continuous(TC=100°C)		3.7	A
Drain Current - Pulsed	I _{DM} ¹	24	A
Single Pulse Avalanche Energy ²	EAS	17.3	mJ
Single Pulse Avalanche Current ²	IAS	12.1	A
Power Dissipation(TC=25°C)	P _D	1.56	W
Power Dissipation - Derate above 25°C		0.012	W/°C
Storage Temperature Range	T _{STG}	-55~ 150	°C
Operating Junction Temperature Range	T _j	-55~ 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Typ.	Unit
Thermal Resistance Junction to ambient	R _{θJA}	---	80	°C/W

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle< 0. 5%.
3. Essentially independent of operating temperature.

Electrical Characteristics(T_j = 25 °C, Unless Otherwise Noted)

Off Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain to Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30	---	---	V
BV _{DSS} Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25 °C , I _D =1mA	---	0.04	---	V/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	---	---	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	---	---	10	μA
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	---	---	±100	nA

On Characteristics

Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =4A	---	20	25	mΩ
		V _{GS} =4.5V, I _D =2A	---	28	42	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.7	2.1	V
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)}		---	-4	---	mV/°C
Forward Transconductance	g _{fs}	V _{DS} =10V, I _S =4A	---	6.5	---	S

Dynamic And Switching Characteristics

Total Gate Charge ^{2,3}	Q _g	V _{DS} =15V, V _{GS} =4.5V, I _D =3A	---	3.7	7	nC
Gate-Source Charge ^{2,3}	Q _{gs}		---	1.48	3	
Gate-Drain Charge ^{2,3}	Q _{gd}		---	1.56	3.5	
Turn-on Delay Time ^{2,3}	T _{d(on)}	V _{DD} =15V, I _D =1A V _{GS} =10V, R _{GEN} =6Ω	---	2.6	5	nS
Turn-on Rise Time ^{2,3}	T _r		---	8.8	16	
Turn-off Delay Time ^{2,3}	T _{d(off)}		---	18.4	35	
Turn-off Fall Time ^{2,3}	T _f		---	5.1	10	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1MHz	---	293	520	pF
Output Capacitance	C _{oss}		---	57	100	
Reverse Transfer Capacitance	C _{rss}		---	40	80	
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	1.15	3	Ω

Drain-Source Diode Characteristics And Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	---	---	5.0	A
Pulsed Source Current	I _{SM}		---	---	24	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25 °C	---	---	1	V

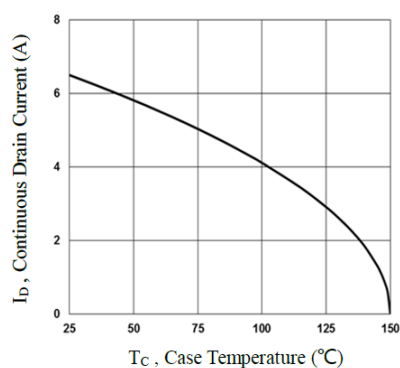


Fig.1 Continuous Drain Current vs. T_c

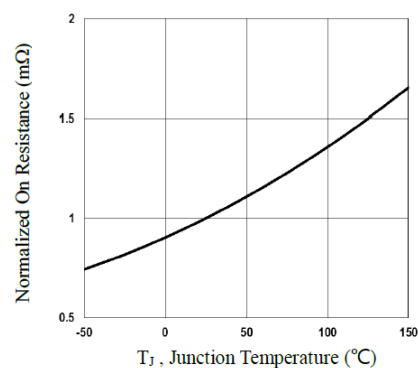


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

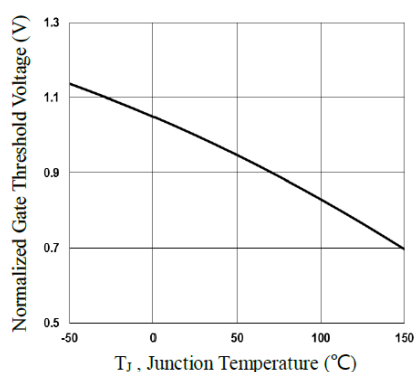


Fig.3 Normalized V_{th} vs. T_j

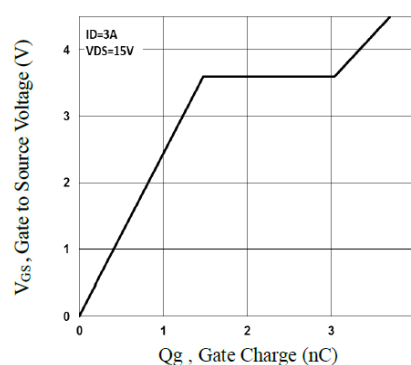


Fig.4 Gate Charge Waveform

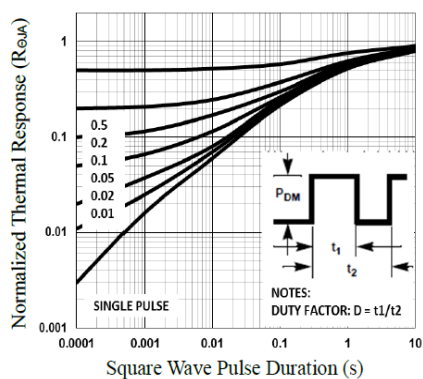


Fig.5 Normalized Transient Response

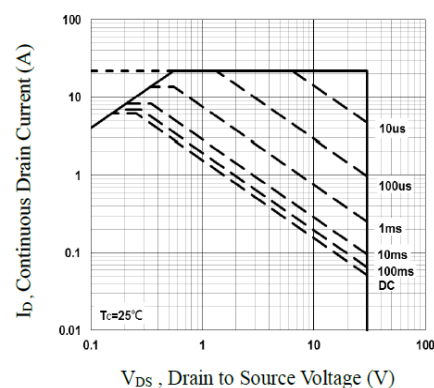


Fig.6 Maximum Safe Operation Area

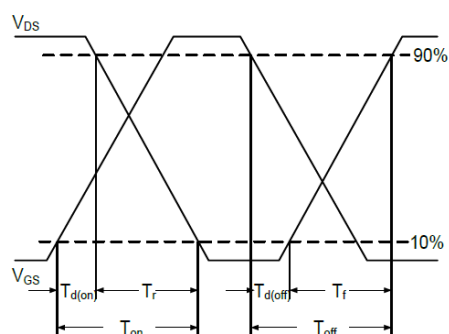


Fig.7 Switching Time Waveform

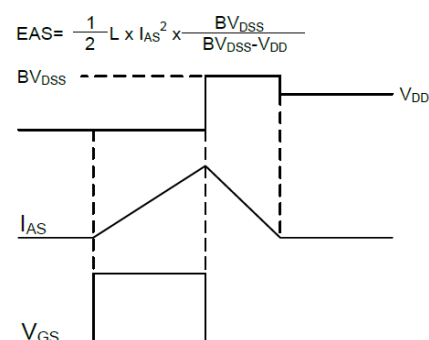
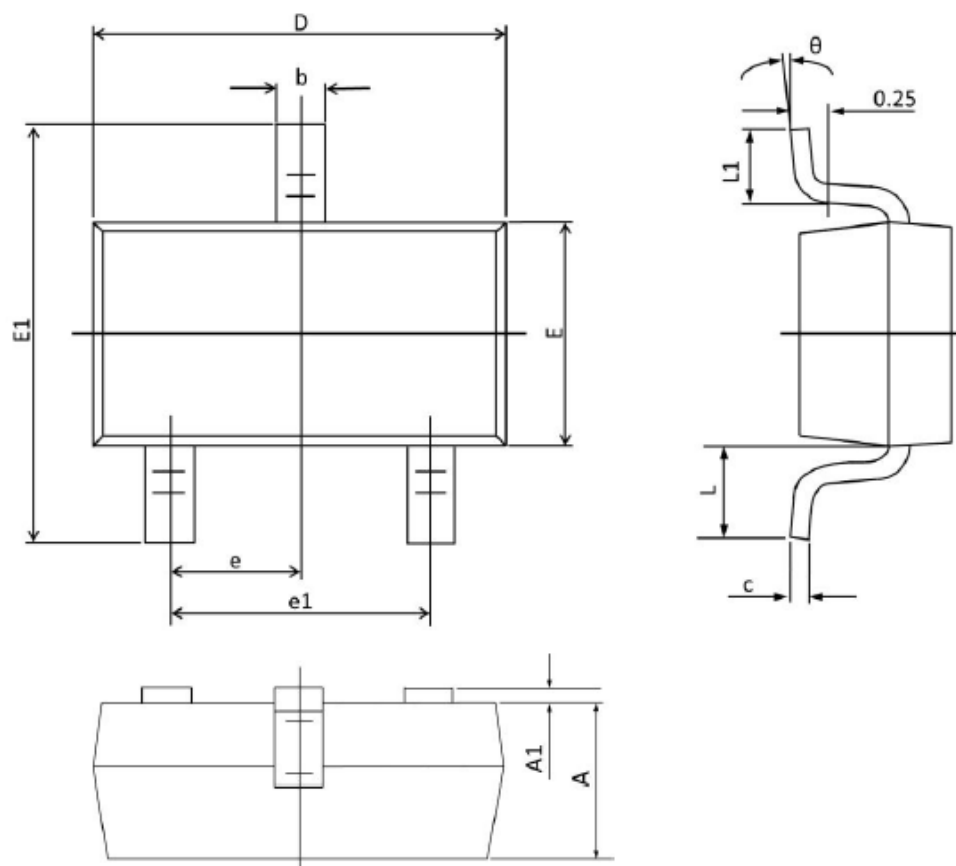


Fig.8 EAS Waveform

SOT23 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.003	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°